

WHAT IS CLAIMED IS:

1. A semiconductor device formed by cutting a first substrate and a second substrate bonded together by a spacer, wherein:

5       the spacer is disposed at an end of the first substrate after cutting;

          the second substrate is a semiconductor wafer formed with a light reception element or elements; and

          the first substrate has an optical element or an  
10       optical element set for converging light on the light reception element or elements.

2. A semiconductor device according to claim 1,  
wherein the first substrate has a compound eye optical  
15       element having a plurality of lenses.

3. A semiconductor device manufacture method comprising:

          a step of bonding a first substrate and a second  
20       substrate by using a spacer; and

          a step of cutting the first and second substrates,  
          wherein said step of cutting the first substrate  
cuts the first substrate at a position where the spacer  
is disposed under the first substrate.

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4. A semiconductor device manufacture method according to claim 3, wherein the second substrate is

formed with a light reception element.

5. A semiconductor device manufacture method according to claim 3, wherein the first substrate is formed with a plurality of lenses.

6. A semiconductor device manufacture method comprising:

a step of holding the semiconductor substrate on a base under a condition that the warp is removed;

a step of bonding an opposing substrate to the semiconductor substrates with a size adjusted according to the warp of the semiconductor substrate; and then

a step of cutting the opposing substrate.

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7. A semiconductor device manufacture method according to claim 6, comprising a step of bonding a plurality of opposing substrates to the semiconductor substrate with a gap of a plurality of opposing substrate corresponding to the size of the warp of the semiconductor substrate.

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8. A semiconductor device manufacture method according to claim 6, wherein said step of bonding the opposing substrate to the semiconductor substrate uses a spacer disposed between the opposing substrate and the semiconductor substrate.

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9. A semiconductor device manufacture method according to claim 6, wherein said step of cutting the opposing substrate cuts an area of the opposing substrate where a spacer is disposed under the opposing substrate.

10. A semiconductor device manufacture method according to claim 6, wherein the semiconductor substrate is formed with a light reception element or elements, and the opposing substrate is formed with an optical element or an optical element set for converging light on the light reception element or elements.

11. A semiconductor device manufacture method according to claim 6, wherein the opposing substrate is formed with a compound eye element having a plurality of lenses.

12. A semiconductor device manufacture method according to claim 6, wherein the semiconductor substrate is a semiconductor wafer.

13. A semiconductor device manufacture method according to claim 6, wherein the opposing substrate has a rectangular shape, a cross shape, a T-character shape, an I-character shape, an L-character shape or a polygonal shape.